

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Necip Berme	05/14/2010
<b>RECEIVING PARTY DATA</b>	
Name:	Bertec Corporation
Street Address:	6171 Huntley Road
Internal Address:	Suite J
City:	Columbus
State/Country:	OHIO
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<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	12780441
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ATTORNEY DOCKET NUMBER:	3993437-135631
NAME OF SUBMITTER:	Richard M. Mescher
Total Attachments: 2 source=assign#page1.tif source=assign#page2.tif	

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**PATENT**  
 REEL: 024388 FRAME: 0066

## ASSIGNMENT

Whereas, I, **Necip Berme**, have jointly invented certain new and useful improvements in a “**Low Profile Transducer with High Moment Capacity**”, for which I am contemporaneously filing a United States patent application (Porter, Wright, Morris & Arthur Docket No. 3993437-135631);

And whereas, **Bertec Corporation**, a corporation of Ohio, having a mailing address of 6171 Huntley Road, Suite J, Columbus, OH 43229, is desirous of acquiring the entire right, title and interest in, to and under said invention and said patent application, any continuing applications, continuations-in-part, divisional applications, refiled or reissue applications made in the United States of America and all other Nations which may result from said invention and information disclosed in said application, and any and all Letters Patent of the United States and other Nations which may be issued therefrom;

Now, therefore, for good and valuable consideration, the receipt of which is hereby acknowledged, I, **Necip Berme** do hereby sell, assign and transfer to **Bertec Corporation** the entire and undivided right, title and interest in and to my invention of new and useful improvements in and to the “**Low Profile Transducer with High Moment Capacity**”, said application for letters patent, the invention therein described, and all rights appurtenant thereto and in all our applications related thereto, including each of the following: the right to apply for any letters patent for said invention in the United States of America and in any and all foreign countries, any and all other applications for letters patent on said invention, in whatsoever countries, including all divisional, renewal, substitute and continuation applications based in whole or in part upon said invention or upon said application or related thereto; any and all letters patent that may issue thereon in the United States and foreign countries and any and all reissues, extensions, renewals, divisions, or continuations of letters patent granted for said inventions or upon said applications, to the full end of the term or terms for which said letters patent may be issued; and every priority or other right accorded by every international convention, treaty or agreement that is or may be predicated upon or arise from said invention, application and other applications or letters patent therefor, all to be held by **Bertec Corporation**, and its successors and assigns, all the same as I would have held and enjoyed had this Assignment not been made.

I hereby authorize and grant the right to **Bertec Corporation** to file and prosecute patent applications in any or all countries on all or any part of said invention in our names or in the name of **Bertec Corporation** or otherwise, as **Bertec Corporation** may deem advisable under any international convention, treaty, or agreement or otherwise.

I hereby request and authorize the Commissioner of Patents and Trademarks of the United States and the empowered officials of all other countries to grant, issue and transfer any letters patent for said invention to **Bertec Corporation**, as assignee of the entire right, title and interest therein, in accordance with this instrument of assignment.

I hereby represent and warrant that there are no outstanding rights or interests inconsistent with the rights and interests granted herein; I covenant that I will not execute, grant, or transfer any rights or interests inconsistent herewith, I bind myself, my heirs, executors, administrators and legal representatives to execute and deliver to **Bertec Corporation**, and its successors and assigns, any further documents or instruments and to perform any and all further acts that may be deemed necessary to enable it, and its successors and assigns, to file applications for letters patent for said invention in any country in which it may elect to file such applications, and to vest in **Bertec Corporation**, and its successors and assigns, the title herein conveyed and intended to so be, and to enable such title to be recorded in the United States and each foreign country in which each such application may be filed so that any patent issued thereon shall be issued to vest in **Bertec Corporation**, and its successors and assigns; and I further covenant and agree, for myself and my executors, administrators and legal representatives, that I and they will, upon request, communicate to **Bertec Corporation**, and its successors and assigns, any facts relating to said invention and the history thereof, known to me or them and that I and they will testify as to the same in any proceeding, interference or litigation when requested to do so by to **Bertec Corporation**, and its successors and assigns.

Inventor: **Necip Berme**

Inventor's Signature: 

Date Signed: 05/14/2010